IN THE CLAIMS:

Claims 1, 4, 7, 10, 13, 16, and 19 have been amended herein. All of the pending claims 1 through 21 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

- 1. (Currently Amended) An automolding system comprising: providing a substrate having a surface having a layer of resist on a portion thereof in the automolding system; and removing at least a portion of the layer of resist and at least a portion of the contaminants from the substrate using a laser in the automolding system; and scanning the substrate using a laser in the automolding system for irregularities from removing the layer of resist.
- 2. (Previously Presented) The automolding system of claim 1, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
- 3. (Previously Presented) The automolding system of claim 1, further comprising: a mold; and encapsulating the substrate in the mold in the automolding system.
- 4. (Currently Amended) A molding system comprising: providing a substrate having a surface having a layer of resist on a portion thereof in the molding system; removing at least a portion of the layer of resist and contaminants from the substrate using a laser in the the molding system; and scanning the substrate using a laser in the automolding system for irregularities from removing the layer of resist.

- 5. (Previously Presented) The molding system of claim 4, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
- 6. (Previously Presented) The molding system of claim 4, further comprising: a mold in the molding system for encapsulating the substrate.
- 7. (Currently Amended) A system for molding comprising: providing a substrate having a surface having a layer of resist on a portion thereof for molding in the system; cutting a portion of the layer of resist using a laser in the molding system; and removing at least a portion of the layer of resist and some contaminants from the substrate using a laser in molding system.
- 8. (Previously Presented) The system of claim 7, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
- 9. (Previously Presented) The system of claim 7, further comprising: a mold in the system for encapsulating the substrate.
- 10. (Currently Amended) An automolding system comprising: placing a substrate having a surface having a layer of resist on a portion thereof in the automolding system; cutting a portion of the layer of resist using a laser in the molding system; and removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.
- 11. (Previously Presented) The automolding system of claim 10, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

- 12. (Previously Presented) The automolding system of claim 10, further comprising: a mold for encapsulating the substrate in the automolding system.
- 13. (Currently Amended) In a molding system comprising: placing a substrate having a semiconductor device thereon, the substrate having a surface having a layer of resist on at least a portion thereof in the molding system; and removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the molding system; and marking a surface of the semiconductor die using the laser in the molding system.
- 14. (Previously Presented) In the molding system of claim 13, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
- 15. (Previously Presented) In the molding system of claim 13, further comprising: a mold in the molding system for encapsulating the substrate.
- 16. (Currently Amended) A system for molding comprising: placing a substrate having a semiconductor device thereon, the substrate having a surface having a layer of resist on at least a portion thereof for molding in the system; and removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system; and marking a surface of the semiconductor device using the laser in the automolding system.
- 17. (Previously Presented) The system of claim 16, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
- 18. (Previously Presented) The system of claim 16, further comprising: a mold in the system for encapsulating the substrate.

19. (Currently Amended) An automolding system having a cleaning apparatus comprising: introducing a substrate having a semiconductor device thereon, the substrate having a surface having a portion thereof covered with a layer of resist in the automolding system; cutting a portion of the layer of resist; and removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system; and marking a surface of the semiconductor device using the laser in the automolding system.

- 20. (Previously Presented) The automolding system of claim 19, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
- 21. (Previously Presented) The automolding system of claim 19, further comprising: a mold for encapsulating the substrate in the automolding system.
 - 22. through 40. (Canceled)